

Application No. 10/757,643  
Response to Office Action

Customer No. 01933

**Amendments to the Specification:**

Please amend the paragraph at page 5, lines 1-9 as follows:

The chip type solid electrolytic capacitor is manufactured as follows. A cathode terminal 105 of a terminal frame 107 is connected to the cathode surface 102b of the capacitor element 101 preliminarily prepared by an electrical conductive adhesive. A contact region where the anode lead 102a of the capacitor element 101 and the anode terminal 104 of the terminal frame 107 are contacted with each other is welded. The capacitor element 101 and the terminal frame 107 are covered with resin by molding so that a part of the anode terminal frame 107 is exposed. The terminal frame 107 is bent along an outer surface of the packaging resin ~~104~~ 103. Thus, the capacitor is manufactured.

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Please amend the paragraph at page 5, line 27 to page 6,  
line 1 as follows:

The anode terminal 14 is connected to the anode lead  
12a of the capacitor element. The cathode terminal 17 is  
connected to the cathode surface ~~12~~ 12b of the capacitor  
element.

Please amend the paragraph at page 6, lines 18-21 as  
follows:

The first anode terminal step 14a has a thickness  
larger than that of the second anode terminal step 14b and  
supports the ~~cathode surface 12b~~ anode lead 12a of the  
capacitor element 11 in the packaging resin 13 with the  
~~cathode surface~~ anode lead 12a electrically connected to the  
anode terminal 14.

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Please amend the paragraph at page 9, lines 8-13 as follows:

Furthermore, the electrical-conductive film applied to the cathode terminal-forming portion 44 is not limited to the Ag plating film 42. For example, an Ag film formed by another general film-forming process except plating can be used. Further, a film made from one of Ag, Au (gold), Cu (copper), and Pd (palladium) can be adopted instead of the Ag film. Still Further, a film made of an alloy including at least one of Ag, Au, Cu, and Pd can be adopted.

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Please amend the paragraph at page 10, lines 16-25 as follows:

As shown in Figs. 9A and 9B, the capacitor element 11 and the anode terminal-forming portion 43 and the cathode terminal-forming portion 44 of the lead frame are covered with the packaging resin 13 so that a part of the anode terminal-forming portion 43 and a part of the cathode terminal-forming portion 44 are exposed from the packaging resin 13. Next, the packaging resin 13 is cut along two cutting surfaces 81 as shown in Fig. 9A and thus the chip as the chip type solid electrolytic capacitor is provided. However, the packaging resin 13 can be cut along four cutting surfaces 81 and 82 as shown in Fig. 9B. When the packaging resin 13 is cut along four surfaces, the volume efficiency of the chip is higher than that of the chip cut along two cutting surfaces.

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And please amend the paragraph at page 11, lines 3-6 as follows:

As shown in Figs. 10A to 10D, an exposed surface of the anode terminal 14 exposed from the first package end surface of the packaging resin 13, that is, a cross sectional surface of the anode terminal 14 perpendicular to the axial direction mentioned above, ~~is~~ has a generally rectangular shape.